



# NPN Transistor Bare Die, 2N3501

Rev 1.0  
31/01/25

**General purpose high voltage amplifier in bare die form**  
Complement to PNP 2N5401

## Features:

- High Breakdown Voltage
- Low  $V_{CE(sat)}$
- Characterized at temperature extremes
- High Reliability Gold Back Metal
- High Reliability tested grades for Military + Space

## Ordering Information:

The following part suffixes apply:

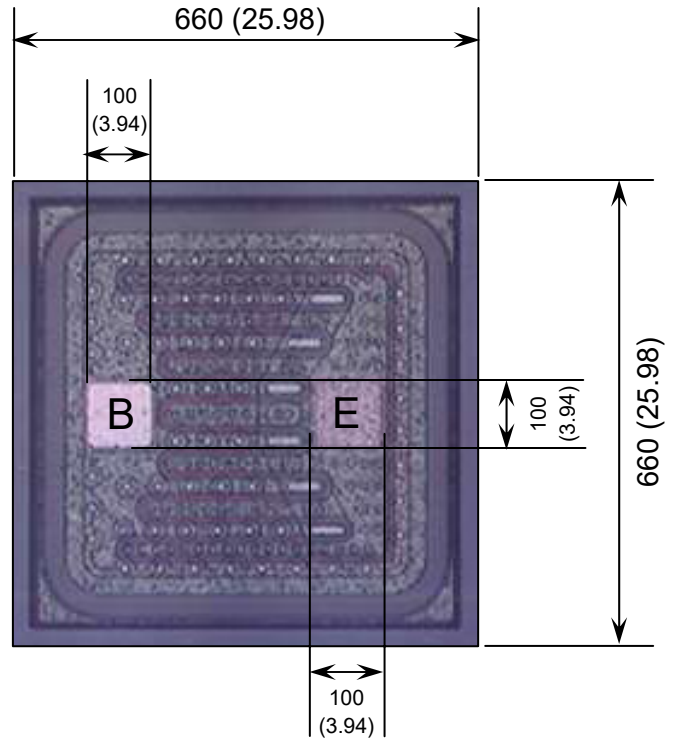
- No suffix - MIL-STD-750 /2072 Visual Inspection
- "H" - MIL-STD-750 /2072 Visual Inspection  
+ MIL-STD-38534 Class H LAT
- "K" - MIL-STD-750 /2072 Visual Inspection  
+ MIL-STD-38534 Class K LAT

LAT = Lot Acceptance Test.

For further information on LAT process flows see below.

[www.siliconsupplies.com/quality/bare-die-lot-qualification](http://www.siliconsupplies.com/quality/bare-die-lot-qualification)

## Die Dimensions in $\mu\text{m}$ (mils)



**E = EMITTER B = BASE**

**DIE BACK = COLLECTOR**

## Supply Formats:

- Default – Die in Waffle Pack (400 per tray capacity)
- Sawn Wafer on Tape – Specific request
- Unsawn Wafer – Specific request
- With additional electrical selection – Specific request
- Sawn as pairs or adjacent pair pick – Specific request

## Mechanical Specification

Die Size (Excluding Saw Street)	660 x 660 25.98 x 25.98	$\mu\text{m}$ mils
Base & Emitter Pad Size	100 x 100 3.94 x 3.94	$\mu\text{m}$ mils
Die Thickness	230 ( $\pm 20$ ) 9.06 ( $\pm 0.79$ )	$\mu\text{m}$ mils
Top Metal Composition	Al - 2.6 $\mu\text{m}$	
Back Metal Composition	AuAs - 0.9 $\mu\text{m}$	





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## Absolute Maximum Ratings $T_A = 25^\circ\text{C}$ unless otherwise stated

PARAMETER	SYMBOL	VALUE	UNIT
Collector-Base Voltage	$V_{CBO}$	150	V
Collector-Emitter Voltage	$V_{CEO}$	150	V
Emitter-Base Voltage	$V_{EBO}$	6	V
Collector Current	$I_C$	300	mA
Junction & Storage Temperature	$T_J, T_{stg}$	150	$^\circ\text{C}$

## Electrical Characteristics $T_A = 25^\circ\text{C}$ unless otherwise stated

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNIT
<b>OFF CHARACTERISTICS</b>						
Collector-Base Breakdown Voltage	$V_{(BR)CBO}$	$I_C = 10\mu\text{A}$	150	-	-	V
Collector-Emitter Breakdown Voltage <sup>1</sup>	$V_{(BR)CEO}$	$I_C = 10\text{mA}$	150	-	-	V
Emitter-Base Breakdown Voltage	$V_{(BR)EBO}$	$I_E = 10\mu\text{A}$	6	-	-	V
Collector Cut-off Current	$I_{CBO}$	$V_{CB} = 75\text{V}$	-	-	50	nA
		$V_{CB} = 150\text{V}$	-	-	10	$\mu\text{A}$
Emitter Cut-off Current	$I_{EBO}$	$V_{EB} = 4\text{V}$	-	-	25	nA
		$V_{EB} = 6\text{V}$	-	-	10	$\mu\text{A}$
<b>ON CHARACTERISTICS<sup>1</sup></b>						
Forward-Current Transfer Ratio	$h_{FE}$	$V_{CE} = 10\text{V}, I_C = 0.1\text{mA}$	35	-	-	-
		$V_{CE} = 10\text{V}, I_C = 1\text{mA}$	50	-	-	-
		$V_{CE} = 10\text{V}, I_C = 10\text{mA}$	75	-	-	-
		$V_{CE} = 10\text{V}, I_C = 150\text{mA}$	100	-	300	-
		$V_{CE} = 10\text{V}, I_C = 300\text{mA}$	20	-	-	-
Collector-Emitter Saturation Voltage	$V_{CE(sat)}$	$I_C = 10\text{mA}, I_B = 1\text{mA}$	-	-	0.2	V
		$I_C = 150\text{mA}, I_B = 15\text{mA}$	-	-	0.4	V
Base Saturation Voltage	$V_{BE(sat)}$	$I_C = 10\text{mA}, I_B = 1\text{mA}$	-	-	0.8	V
		$I_C = 150\text{mA}, I_B = 15\text{mA}$	-	-	1.2	V
<b>SMALL SIGNAL CHARACTERISTICS<sup>2</sup></b>						
Forward Current Transfer Ratio	$ h_{fe} $	$V_{CE} = 20\text{V}, I_C = 20\text{mA}, f = 100\text{MHz}$	1.5	-	8.0	-
Output Capacitance	$C_{obo}$	$V_{CB} = 10\text{V}, I_E = 0, 100\text{kHz} \leq f \leq 1\text{MHz}$	-	-	8.0	pF
Input Capacitance	$C_{ibo}$	$V_{EB} = 0.5\text{V}, I_C = 0, 100\text{kHz} \leq f \leq 1\text{MHz}$	-	-	80	pF
<b>SWITCHING CHARACTERISTICS<sup>2</sup></b>						
Turn-On Time	$t_{on}$	$V_{EB} = 5\text{V}, I_C = 150\text{mA}, I_{B1} = 15\text{mA}$	-	-	115	ns
Turn-Off Time	$t_{off}$	$I_C = 150\text{mA}, I_{B1} = I_{B2} = -15\text{mA}$	-	-	1150	ns

1. Pulse Test: pulse width = 300 $\mu\text{s}$ , duty cycle < 2.0% 2. Not production testing in die form, characterized by chip design & package verification.





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